



an Open Access Journal by MDPI

Hardware-Aware Deep Learning

Guest Editors:

Dr. Deliang Fan

School of Electrical, Computer and Energy Engineering, Arizona State University (ASU), Tempe, AZ, USA

Dr. Zhezhi He

Department of Computer Science and Engineering, Shanghai Jiao Tong University, Shanghai 00240, China

Dr. Alessandro Bruno

Department of Biomedical Sciences, Humanitas University, Via Rita Levi Montalcini 4, Pieve Emanuele, 20072 Milan, Italy

Deadline for manuscript submissions:

closed (20 May 2023)

Message from the Guest Editors

One of the main factors that contributes to the success of deep learning (DL) is the mighty computing power provided by modern hardware, spanning from high-performance server systems to resource-limited edge devices. The edge side (e.g., embedded systems, IoT) demands not only extreme energy-efficiency but also real-time inference capability, which requires cross-stack techniques, including model compression, compilation, architecture and circuit design of AI chips, emerging devices, etc. On the cloud side, as the DL model size grows exponentially in the last two years (e.g., OpenAI GPT3, Google switch-transformer, etc.), how to efficiently support the training and inference of those immense models is also an emerging research direction. Without lowering their hardware cost, however, incorporating them into the paradigm of machine learning as a service (MLaaS) will be infeasible. Therefore, the aforementioned concerns motivate the research of hardware-aware deep learning, for optimized energy, latency, and even security.



mdpi.com/si/89381

Special Issue



an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Inspec, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q1 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Contact Us

Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](#)